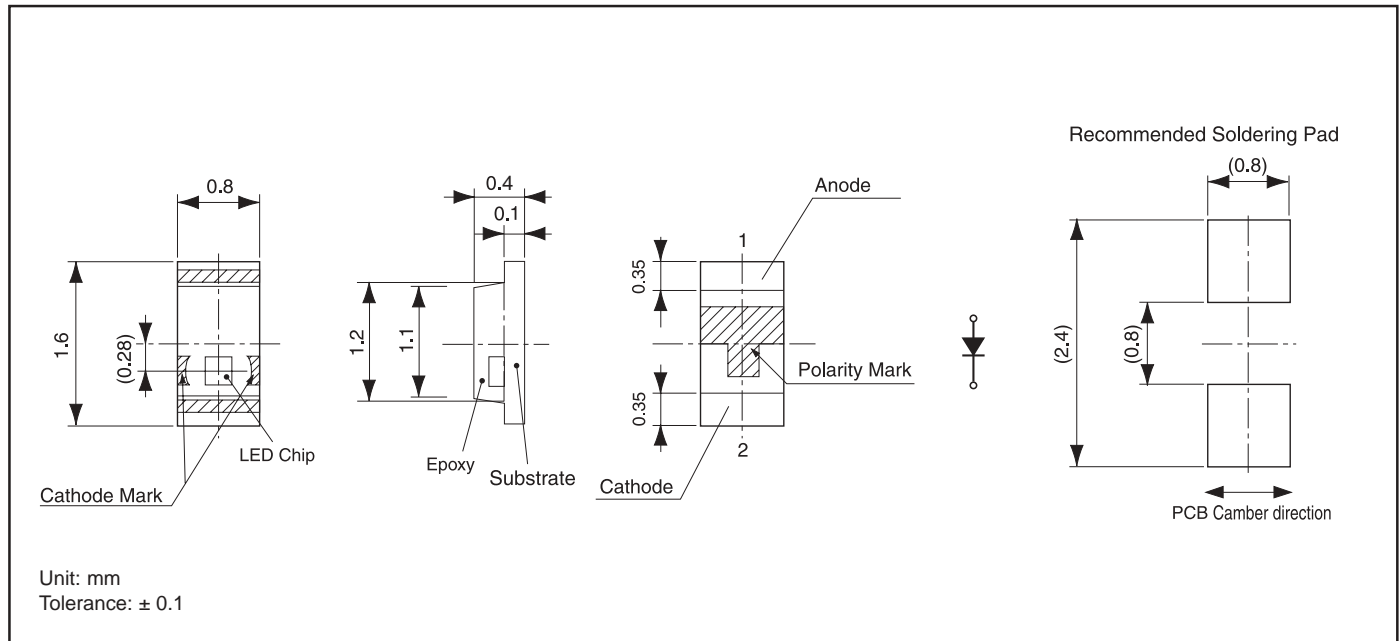## ■ Features

- Super thin type: height is only 0.4mm
- Excellent for applications where saving space is critical

■ Applications

- Cellular phone keyboard backlighting
- Backlighting for switches

■ Outline Dimensions

Preliminary

Recommended Soldering Pad

Anode

Polarity Mark

Cathode

1

2

LED Chip

Cathode Mark

Epoxy

Substrate

PCB Camber direction

Unit: mm
Tolerance: ± 0.1

■ Electro-Optical Characteristics

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Luminous Intensity Iv			Wavelength				Forward Voltage VF			Reverse Current IR		Viewing Angle (2 θ 1/2)
				MIN.	TYP.	IF	Peak λp TYP.	Dominant λd TYP.	Spectral Line Half Width Δλ TYP.	IF	TYP.	MAX.	IF	MAX.	VR	
PY1114CK	GaP	Yellow-Green	Milky White	3.3	5.6	10	570	572	30	10	2.1	2.8	10	100	4	140°
Unit				mcd		mA	nm			mA	V		mA	μA	V	Deg.

◼ Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Yellow	Unit
		PY	
Power Dissipation	Pd	75	mW
Forward Current	I_F	25	mA
Peak Forward Current	I_{FM}	60	mA
Reverse Voltage	V_R	4	V
Operating Temperature	Topr	-40 to +85	°C
Storage Temperature	Tstg	-40 to +100	°C
Derating*	ΔI_F	0.36 (DC) 0.86 (Pulse)	mA/°C

* Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤1/20.

◼ Operation Current Derating Chart (DC)

AMBIENT TEMP. vs FORWARD CURRENT
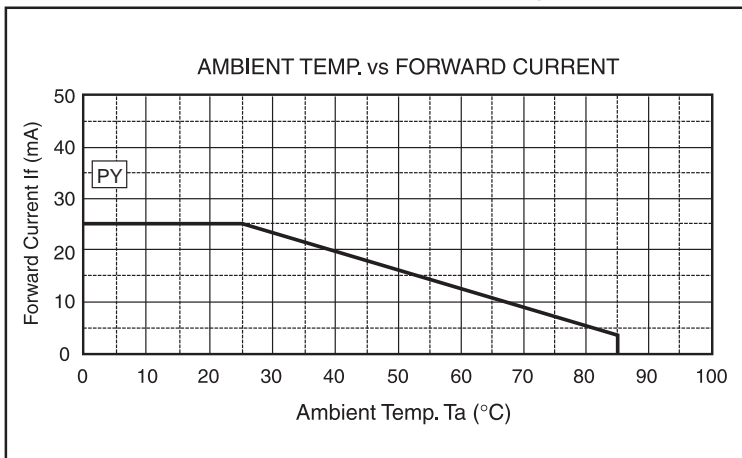
◼ Spatial Distribution

◼ Taping Specifications


Quantity on tape:
4000 pieces
per reel
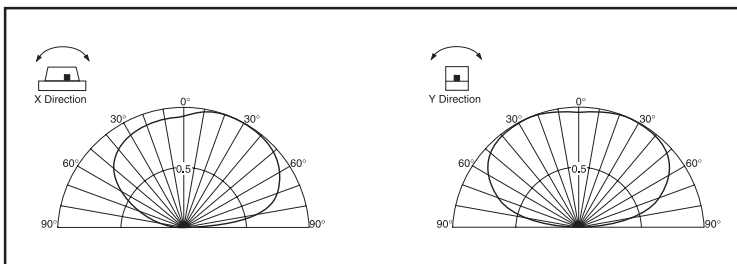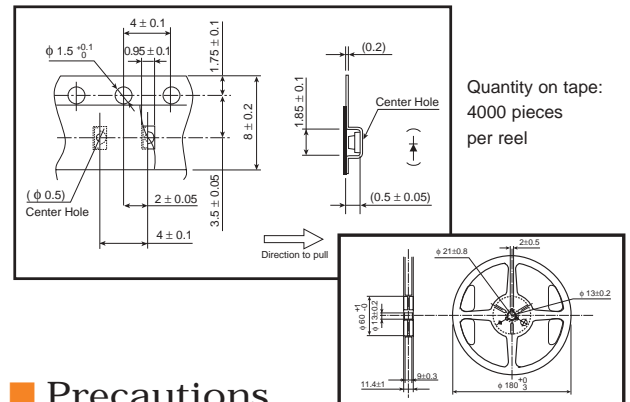
◼ Precautions

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- Soldering iron: Temperature at tip of iron: 350°C max. (30W max.)
  Soldering time: 3 sec. max.

- Dip soldering: Preheating: 120°C max. (resin surface temp.)
  60 sec. max. Bath temperature: 265°C max. Dipping Time: 5 sec. max.

- Reflow Soldering:
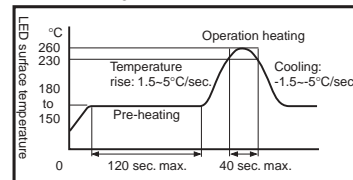
2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.

- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.

- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PY1114CK-0102